



(51) International Patent Classification:

H01L 21/68 (2006.01) C30B 25/16 (2006.01)
H01L 21/67 (2006.01) C23C 16/458 (2006.01)
H01L 21/687 (2006.01) C23C 16/52 (2006.01)
C30B 25/12 (2006.01)

(21) International Application Number:

PCT/US2023/011027

(22) International Filing Date:

18 January 2023 (18.01.2023)

(25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data:

63/392,796 27 July 2022 (27.07.2022) US

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(81) Designated States (unless otherwise indicated, for every
kind of national protection available): AE, AG, AL, AM,
AO, AT, AU, AZ, BA, BB, BG, BH, BN, BR, BW, BY, BZ,
CA, CH, CL, CN, CO, CR, CU, CV, CZ, DE, DJ, DK, DM,
DO, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, GT,
HN, HR, HU, ID, IL, IN, IQ, IR, IS, IT, JM, JO, JP, KE,
KG, KH, KN, KP, KR, KW, KZ, LA, LC, LK, LR, LS, LU,
LY, MA, MD, MG, MK, MN, MW, MX, MY, MZ, NA, NG,
NI, NO, NZ, OM, PA, PE, PG, PH, PL, PT, QA, RO, RS,
RU, RW, SA, SC, SD, SE, SG, SK, SL, ST, SV, SY, TH, TJ,
TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, WS, ZA,
ZM, ZW.

(84) Designated States (unless otherwise indicated, for every
kind of regional protection available): ARIPO (BW, CV,
GH, GM, KE, LR, LS, MW, MZ, NA, RW, SC, SD, SL, ST,
SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ,
RU, TJ, TM), European (AL, AT, BE, BG, CH, CY, CZ,
DE, DK, EE, ES, FI, FR, GB, GR, HR, HU, IE, IS, IT, LT,
LU, LV, MC, ME, MK, MT, NL, NO, PL, PT, RO, RS, SE,
SI, SK, SM, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN,
GQ, GW, KM, ML, MR, NE, SN, TD, TG).

(54) Title: SYSTEM AND METHOD FOR AUTO CORRECTION OF SUBSTRATE MISALIGNMENT

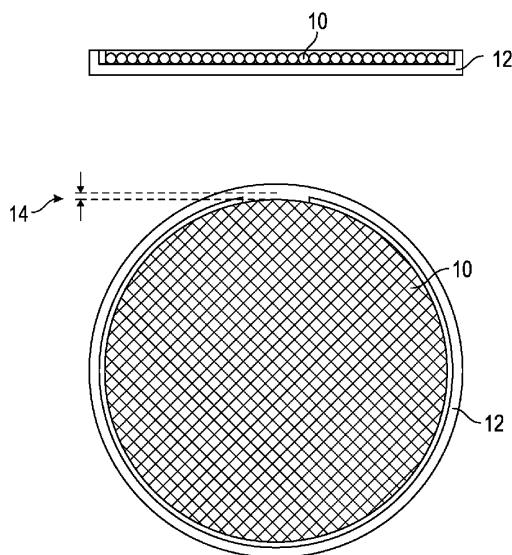


FIG. 1

(57) Abstract: Embodiments described herein relate semiconductor manufacturing and processing. More particularly, a processing system for auto correcting misalignments of substrates in process chambers is provided. The processing system includes a process chamber having a substrate support disposed within a chamber volume of the process chamber. The substrate support includes a pocket for receiving a substrate, and a plurality of flow conduits extending between a top surface of the pocket and a bottom surface of the substrate support. An imaging device is coupled to the process chamber and configured to monitor a position of a substrate when loaded in the pocket of the substrate support.

Published:

— with international search report (Art. 21(3))